

NTC thermistors for temperature measurement

Probe assemblies

Series/Type: B57276K Date: January 2018

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Temperature measurement

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Applications

- Washing machines
- Dish washers
- Tumble-dryers
- Water boilers

Features

- Suitable for use in corrosive environments
- Compact stainless steel case
- RAST 2.5 or RAST 5 connector
- Cost-effective ready-to-use sensor
- UL approval (E69802)
- VDE approval (DIN EN 60539-1: 2002)

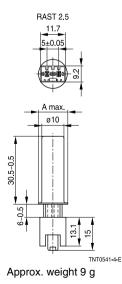
Options

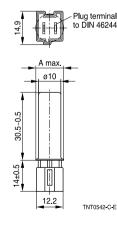
- Alternative resistance ratings, rated temperatures and resistance tolerances available on request.
- RAST 5 plug terminals or RAST 2.5 connector with bar available on request.
- Type Z276, Z277 and Z278 with different geometry and faster response time available on request.

Delivery mode

Bulk

Dimensional drawings





RAST 5

Dimensions

R ₆₀	A max.	Plug terminal	
Ω	mm	mm	
RAST 2.5 connector			
1204	Ø 14.5	-	
3243	Ø 12.4	-	
RAST 5 connector			
1082	Ø 14.5	6.3 x 0.8	
3243	Ø 12.4	4.8 x 0.8	

Approx. weight 9 g

Please read *Cautions and warnings* and *Important notes* at the end of this document.

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General technical data

Climatic category	(IEC 60068-1)		10/100/56	
Max. power	(at 25 °C)	P ₂₅	500	mW
Resistance tolerance		$\Delta R_{\rm B}/R_{\rm B}$	±2	%
Dissipation factor	(in water)	δ_{th}	approx. 20	mW/K
Thermal time constant	(in water)	$ au_{a}$	approx. 20	s
Heat capacity		C _{th}	approx. 500	mJ/K
Insulation resistance	(V = 100 V DC)	R _{ins}	> 1000	MΩ
Test voltage	(t = 1 s)	V _{test}	3750	V AC

Electrical specification and ordering codes

T _R	R _R	R ₂₅	No. of R/T	B _{25/100}	Ordering code
°C	Ω	Ω	characteristic	К	
RAST 2.5 conr	nector				
60	1204	4829	2003	3980 ±1%	B57276K0482A007
60	3243	11981	2901	3760 ±1.5%	B57276K0123A028
RAST 5 connector					
63	1082	4829	2003	3980 ±1.5%	B57276K0482A009
60	3243	11981	2901	3760 ±1.5%	B57276K0123A024

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Reliability data

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature T: 100 °C t: 1000 h	< 2%	No visible damage
Storage in damp heat, steady state	IEC 60068-2-78	Temperature of air: 40 °C Relative humidity of air: 93% Duration: 56 days	< 1%	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: -10 °C < 1% Upper test temperature: 100 °C Number of cycles: 10		No visible damage
Endurance		P _{max} : 500 mW t: 1000 h	< 2%	No visible damage
Long-term stability (empirical value)		Temperature: 100 °C t: 10000 h	< 3%	No visible damage
Robustness of terminations	DIN 46 249	Pull-out force (both connectors together) F = 50 N		No visible damage

Note

- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals).
- Avoid dewing and condensation unless thermistor is specified for these conditions.

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R/T characteristics

R/T No.	2003		2901	
T (°C)	B _{25/100} = 3980 K		$B_{25/100} = 3760 \text{ K}$	(
	R _T /R ₂₅	α (%/K)	R _T /R ₂₅	α (%/K)
-55.0	97.578	7.5	63.969	6.7
-50.0	67.65	7.2	46.179	6.4
-45.0	47.538	7.0	33.738	6.2
-40.0	33.831	6.7	24.927	6.0
-35.0	24.359	6.5	18.611	5.8
-30.0	17.753	6.3	14.033	5.6
-25.0	13.067	6.0	10.679	5.4
-20.0	9.7228	5.8	8.198	5.3
-15.0	7.3006	5.6	6.3123	5.2
-10.0	5.5361	5.5	4.9014	5.1
-5.0	4.2332	5.3	3.821	4.9
0.0	3.266	5.1	3.0027	4.7
5.0	2.5392	5.0	2.3801	4.6
10.0	1.9902	4.8	1.9	4.5
15.0	1.5709	4.7	1.5257	4.3
20.0	1.2492	4.5	1.233	4.3
25.0	1.0000	4.4	1.0000	4.1
30.0	0.80575	4.3	0.81679	4.0
35.0	0.65326	4.1	0.67166	3.9
40.0	0.5329	4.0	0.55527	3.8
45.0	0.43715	3.9	0.46095	3.8
50.0	0.36064	3.8	0.38459	3.7
55.0	0.29908	3.7	0.32184	3.6
60.0	0.24932	3.6	0.27068	3.5
65.0	0.20886	3.5	0.22907	3.3
70.0	0.17578	3.4	0.19468	3.2
75.0	0.14863	3.3	0.16607	3.1
80.0	0.12621	3.2	0.14221	3.1
85.0	0.10763	3.1	0.12218	3.0
90.0	0.092159	3.1	0.10533	2.9
95.0	0.079225	3.0	0.09123	2.8
100.0	0.068356	2.9	0.079284	2.8
105.0	0.059247	2.8	0.069062	2.7
110.0	0.051531	2.8	0.06034	2.7
115.0	0.044921	2.7	0.052886	2.6
120.0	0.039282	2.7	0.046482	2.5
125.0	0.034387	2.6	0.040985	2.5
130.0	0.030186	2.5	0.036233	2.5
135.0	0.02665	2.5	0.032101	2.4
140.0	0.023594	2.4	0.02851	2.4
145.0	0.020931	2.4	0.025373	2.3
150.0	0.018616	2.3	0.022633	2.3
155.0	0.016612	2.3	0.020231	2.3

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Cautions and warnings

General

See "Important notes" on page 2.

Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature -25 °C ... +45 °C, relative humidity ≤75% annual mean, <95% maximum 30 days per annum, dew precipitation is inadmissible.</p>
- Do not store thermistors where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or components may stick together, causing problems during mounting.
- Avoid contamination of thermistor surface during storage, handling and processing.
- Avoid storage of thermistors in harmful environments like corrosive gases (SO_x, Cl etc).
- Use the components as soon as possible after opening the original packaging.
- Solder thermistors within the time specified after shipment from EPCOS. For leaded components this is 24 months, for SMD components with nickel barrier termination 12 months, for leadless components this is 12 months, for SMD components with AgPd termination 6 months.

Handling

- NTC thermistors must not be dropped. Chip-offs or any other damage must not be caused during handling of NTCs.
- Do not touch components with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

Bending / twisting leads

A lead (wire) may be bent at a minimum distance of twice the wire's diameter plus 4 mm from the component head or housing. When bending ensure the wire is mechanically relieved at the component head or housing. The bending radius should be at least 0.75 mm.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

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Mounting

- Ensure that no thermo-mechanical stress occurs due to production processes (curing or overmolding processes) when thermistors are sealed, potted or overmolded or during their subsequent operation. The maximum temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing/potting compound and plastic material) are chemically neutral.
- Electrodes/contacts must not be scratched or damaged before/during/after the mounting process.
- Contacts and housing used for assembly with the thermistor must be clean before mounting.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Avoid contamination of the thermistor surface during processing.
- The connections of sensors (e.g. cable end, wire end, plug terminal) may only be exposed to an environment with normal atmospheric conditions.
- Tensile forces on cables or leads must be avoided during mounting and operation.
- Bending or twisting of cables or leads directly on the thermistor body is not permissible.
- Avoid using chemical substances as mounting aids. It must be ensured that no water or other liquids enter the NTC thermistors (e.g. through plug terminals). In particular, water based substances (e.g. soap suds) must not be used as mounting aids for sensors.
- The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified power range.
- Environmental conditions must not harm the thermistors. Only use the thermistors under normal atmospheric conditions or within the specified conditions.
- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. perfluoropolyethers such as Galden).
- Avoid dewing and condensation unless thermistor is specified for these conditions.
- Bending or twisting of cables and/or wires is not permissible during operation of the sensor in the application.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

Display of ordering codes for EPCOS products

The ordering code for one and the same EPCOS product can be represented differently in data



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sheets, data books, other publications, on the EPCOS website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes



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Symbols and terms

Symbol	English	German
А	Area	Fläche
AWG	American Wire Gauge	Amerikanische Norm für Drahtquerschnitte
В	B value	B-Wert
B _{25/100}	B value determined by resistance	B-Wert, ermittelt durch Widerstands-
	measurement at 25 °C and 100 °C	messungen bei 25 °C und 100 °C
C _{th}	Heat capacitance	Wärmekapazität
I	Current	Strom
Ν	Number (integer)	Anzahl (ganzzahliger Wert)
P ₂₅	Maximum power at 25 °C	Maximale Leistung bei 25 °C
P_{diss}	Power dissipation	Verlustleistung
P _{el}	Electrical power	Elektrische Leistung
P _{max}	Maximum power within stated	Maximale Leistung im
	temperature range	angegebenenTemperaturbereich
$\Delta R_{B}/R_{B}$	Resistance tolerance caused by	Widerstandstoleranz, die durch die
	spread of B value	Streuung des B-Wertes verursacht wird
R _{ins}	Insulation resistance	Isolationswiderstand
R _P	Parallel resistance	Parallelwiderstand
R _R	Rated resistance	Nennwiderstand
$\Delta R_R/R_R$	Resistance tolerance	Widerstandstoleranz
R _s	Series resistance	Serienwiderstand
R_{T}	Resistance at temperature T	Widerstand bei Temperatur T
	(e.g. R_{25} = resistance at 25 °C)	(z.B. R ₂₅ = Widerstand bei 25 °C)
Т	Temperature	Temperatur
ΔT	Temperature tolerance	Temperaturtoleranz
t —	Time	Zeit
	Ambient temperature	Umgebungstemperatur
T _{max}	Upper category temperature	Obere Grenztemperatur
T _{min}		(Kategorietemperatur) Untere Grenztemperatur
I min	Lower category temperature	(Kategorietemperatur)
т	Operating temperature	
Т _{ор} т	Operating temperature	Betriebstemperatur
T _R T _{surf}	Rated temperature Surface temperature	Nenntemperatur Oberflächentemperatur
V	Voltage	Spannung
V _{ins}	Insulation test voltage	Isolationsprüfspannung
V _{op}	Operating voltage	Betriebsspannung
V _{test}	Test voltage	Prüfspannung



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Symbol	English	German
α	Temperature coefficient	Temperaturkoeffizient
Δ	Tolerance, change	Toleranz, Änderung
δ_{th}	Dissipation factor	Wärmeleitwert
$ au_c$ $ au_a$	Thermal cooling time constant Thermal time constant	Thermische Abkühlzeitkonstante Thermische Zeitkonstante

Abbreviations / Notes

Symbol	English	German
SMD	Surface-mounted devices	Oberflächenmontierbares Bauelement
*	To be replaced by a number in ordering codes, type designations etc.	Platzhalter für Zahl im Bestellnummern- code oder für die Typenbezeichnung.
+	To be replaced by a letter.	Platzhalter für einen Buchstaben.
	All dimensions are given in mm.	Alle Maße sind in mm angegeben.
	The commas used in numerical values denote decimal points.	Verwendete Kommas in Zahlenwerten bezeichnen Dezimalpunkte.



The following applies to all products named in this publication:

- 1. Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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Important notes

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